

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/148,723 ✓
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Reference - - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the reference listed on the attached Form PTO-1449. No admission is made regarding whether the submitted reference is prior art.

Citation of this reference is respectfully requested.

Respectfully submitted, ,

Date:

April 17, 2001



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